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|--|--|---|----------------------------------|--------------|
| PCN Number: | 20210326003.1 | | PCN Date: | Mar 31, 2021 |
| Title: | Transfer of select C10 devices from ANAM-1 to DMOS5 Wafer Fab site | | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services | |
| Proposed 1st Ship Date: | Jun 30, 2021 | Estimated Sample Availability: | Date provided at sample request. | |
| Change Type: | | | | |
| <input type="checkbox"/> Assembly Site | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Assembly Materials | | |
| <input type="checkbox"/> Design | <input type="checkbox"/> Electrical Specification | <input type="checkbox"/> Mechanical Specification | | |
| <input type="checkbox"/> Test Site | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Process | | |
| <input type="checkbox"/> Wafer Bump Site | <input type="checkbox"/> Wafer Bump Material | <input type="checkbox"/> Wafer Bump Process | | |
| <input checked="" type="checkbox"/> Wafer Fab Site | <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Wafer Fab Process | | |
| | <input type="checkbox"/> Part number change | | | |

PCN Details

Description of Change:

This change notification is to announce the transfer of select devices from ANAM-1 to the DMOS5 Wafer Fab site. Fab support from ANAM-1 has been discontinued. Buffer inventory has been built to cover the notification period of this change notification.

| Current (Discontinued) | | | New (Transfer to Location) | | |
|------------------------|-------------|----------------|----------------------------|-------------|----------------|
| Current Fab Site | Fab Process | Wafer Diameter | New Fab Site | Fab Process | Wafer Diameter |
| ANAM-1 | C10 | 200mm | DMOS5 | C10 | 200mm |

Qual details are provided in the Qual Data Section.

Reason for Change:

Discontinued Fab support from ANAM-1

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

| Chip Site | Chip Site Origin (20L) | Chip Site Country Code (21L) | Chip Site City |
|-----------|------------------------|------------------------------|----------------|
| ANAM-1 | ANM | KOR | Bucheon-si |

New Fab Site

| Chip Site | Chip Site Origin (20L) | Chip Site Country Code (21L) | Chip Site City |
|---------------|------------------------|------------------------------|----------------|
| DP1DM5 | DM5 | USA | Dallas |

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY(1T) 7523483S12
 (P)
 (2P) REV: SHE (V) 0033517
 (20L) CS0: SHE (21L) CCO: USA
 (22L) ACO: MYS (23L) ACO: MYS

Product Affected Group:

| | | | |
|----------------|----------------|----------------|----------------|
| CDCLVD1204RGTR | CDCLVD1204RGTT | CDCLVD2108RGZR | CDCLVD2108RGZT |
|----------------|----------------|----------------|----------------|

Qualification Report

Approve Date 23-March-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | Test Name / Condition | Duration | Qual Device: CDCLVD2108RGZ | Qual Device: CDCLVD1204RGT | QBS Reference: TLK2500IRCP | QBS Reference: TLK2201BIRCP |
|------|-------------------------------|---------------------------|-------------------------------|-------------------------------|-------------------------------|--------------------------------|
| AC | Autoclave 121C, 2atm | 96 Hours | - | - | 3/231/0 | 3/231/0 |
| CDM | ESD - CDM | 1500 V | - | - | - | 1/3/0 |
| ED | Electrical Characterization | Per Data Sheet Parameters | - | - | Pass | Pass |
| HAST | Biased HAST, 130C/85%RH | 96 Hours | - | - | 3/231/0 | - |
| HBM | ESD - HBM | 4000 V | - | - | - | 1/3/0 |
| HTOL | Life Test, 155C | 240 Hours | - | - | 3/231/0 | - |
| HTSL | High Temp. Storage Bake, 170C | 420 Hours | - | - | 3/135/0 | 3/135/0 |
| LU | Latch-up | (Per JESD78) | - | - | - | 1/6/0 |
| T/C | Temp Cycle -65C/150C | 500 Cycles | - | - | - | 3/231/0 |
| WBP | Bond Pull | Wires | Pass | Pass | - | - |
| WPS | Ball Bond Shear | Wires | Pass | Pass | - | - |

- Qual Devices qualified at LEVEL3-260C: CDCLVD2108RGZ

- Qual Devices qualified at LEVEL2-260C: CDCLVD1204RGT

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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